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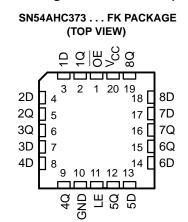
- Operating Range 2-V to 5.5-V V<sub>CC</sub>
- Latch-Up Performance Exceeds 250 mA Per JESD 17

SN54AHC373...J OR W PACKAGE SN74AHC373...DB, DGV, DW, N, NS, OR PW PACKAGE (TOP VIEW)

<u>oe</u> [	1	ر 20	] v <sub>cc</sub>
1Q [	2	19	] 8Q
1D [	3	18	] 8D
2D [	4	17	]7D
2Q [	5	16	] 7Q
3Q [	6	15	] 6Q
3D [	7	14	] 6D
4D [	8	13	] 5D
4Q [	9	12	] 5Q
GND [	10	11	LE



- 200-V Machine Model (A115-A)
- 1000-V Charged-Device Model (C101)



### description/ordering information

The 'AHC373 devices are octal transparent D-type latches designed for 2-V to 5.5-V V<sub>CC</sub> operation.

When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is low, the Q outputs are latched at the logic levels of the D inputs.

A buffered output-enable ( $\overline{OE}$ ) input can be used to place the eight outputs in either a normal logic state (high or low) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

т <sub>А</sub>	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74AHC373N	SN74AHC373N
	SOIC - DW	Tube	SN74AHC373DW	410272
	50IC - DVV	Tape and reel	SN74AHC373DWR	NUMBER MARKING   IC373N SN74AHC373N   IC373DW AHC373   IC373DWR AHC373   IC373DWR AHC373   IC373DBR HA373   IC373PWR HA373   IC373DQVR HA373   IC373DWR HA373   IC373DWR HA373   IC373DWR HA373   IC373DQVR HA373   IC373JQVR HA373   IC373JQVR SNJ54AHC373J   HC373W SNJ54AHC373W
–40°C to 85°C	SOP – NS	Tape and reel	SN74AHC373NSR	AHC373
-40°C 10 85°C	SSOP – DB	Tape and reel	SN74AHC373DBR	HA373
	TSSOP – PW	Tube	SN74AHC373PW	114.272
	1330P - PW	Tape and reel	SN74AHC373PWR	HA373
	TVSOP – DGV	Tape and reel	SN74AHC373DGVR	HA373
	CDIP – J	Tube	SNJ54AHC373J	SNJ54AHC373J
–55°C to 125°C	CFP – W	Tube	SNJ54AHC373W	SNJ54AHC373W
	LCCC – FK	Tube	SNJ54AHC373FK	SNJ54AHC373FK

#### **ORDERING INFORMATION**

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



Copyright © 2003, Texas Instruments Incorporated On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

### SN54AHC373, SN74AHC373 OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS SCLS235I – OCTOBER 1995 – REVISED JULY 2003

### description/ordering information (continued)

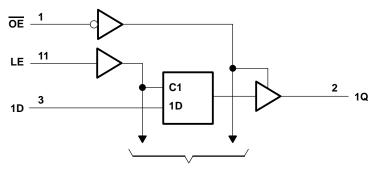
OE does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to V<sub>CC</sub> through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

_		ch latch)	
	INPUTS	OUTPUT	
OE	LE	D	Q
L	Н	Н	Н
L	н	L	L
L	L	Х	Q <sub>0</sub>
Н	Х	Х	z

FUNCTION TADLE

## logic diagram (positive logic)



To Seven Other Channels

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Input voltage range, V <sub>I</sub> (see Note 1) Output voltage range, V <sub>O</sub> (see Note 1) Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0) Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> ) Continuous output current, I <sub>O</sub> (V <sub>O</sub> = 0 to V <sub>CC</sub> ) Continuous current through V <sub>CC</sub> or GND Package thermal impedance, $\theta_{JA}$ (see Note 2): D D N N P	-0.5 V to 7 V -0.5 V to 7 V -0.5 V to 7 V -0.5 V to V <sub>CC</sub> + 0.5 V -20 mA ±20 mA ±25 mA ±75 mA DB package 70°C/W OGV package 92°C/W W package 69°C/W IS package 60°C/W W package 60°C/W
Storage temperature range, Istg	

<sup>+</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



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### recommended operating conditions (see Note 3)

			SN54A	HC373	SN74A	HC373		
			MIN	MAX	MIN MAX		UNIT	
VCC	Supply voltage		2	5.5	2	5.5	V	
		V <sub>CC</sub> = 2 V	1.5		1.5			
VIH	High-level input voltage	V <sub>CC</sub> = 3 V	2.1		2.1		V	
		V <sub>CC</sub> = 5.5 V	3.85		3.85			
		$V_{CC} = 2 V$		0.5		0.5		
VIL	Low-level input voltage	$V_{CC} = 3 V$		0.9		0.9	V	
		V <sub>CC</sub> = 5.5 V		1.65		1.65		
VI	Input voltage		0	5.5	0	5.5	V	
VO	Output voltage		0	VCC	0	VCC	V	
		$V_{CC} = 2 V$		-50		-50	μA	
ЮН	High-level output current	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		-4		-4	A	
		$V_{CC}$ = 5 V ± 0.5 V		-8		-8	mA	
		$V_{CC} = 2 V$		50		50	μΑ	
IOL	Low-level output current	$V_{CC}$ = 3.3 V ± 0.3 V		4		4	A	
		$V_{CC}$ = 5 V ± 0.5 V		8		8	mA	
A # / A	Insuit transition rise or fell rote	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		100		100	20/1	
$\Delta t / \Delta v$	Input transition rise or fall rate	$V_{CC}$ = 5 V ± 0.5 V		20		20	ns/V	
TA	Operating free-air temperature	·	-55	125	-40	85	°C	

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	Vaa	Т	<b>Α = 25°C</b>		SN54A	HC373	SN74A	HC373	UNIT
PARAMETER	TEST CONDITIONS	Vcc	MIN	TYP N	IAX	MIN	MAX	MIN	MAX	UNIT
		2 V	1.9			1.9		1.9		
	I <sub>OH</sub> = -50 μA	3 V	2.9			2.9		2.9		
∨он		4.5 V	4.4			4.4		4.4		V
	$I_{OH} = -4 \text{ mA}$	3 V	2.58			2.48		2.48		
	I <sub>OH</sub> = -8 mA	4.5 V	3.94			3.8		3.8		
		2 V			0.1		0.1		0.1	
	I <sub>OL</sub> = 50 μA	3 V			0.1		0.1		0.1	
VOL		4.5 V			0.1		0.1		0.1	V
	I <sub>OL</sub> = 4 mA	3 V		(	0.36		0.5		0.44	
	I <sub>OL</sub> = 8 mA	4.5 V		(	0.36		0.5		0.44	
Ц	$V_{I} = 5.5 V \text{ or GND}$	0 V to 5.5 V		đ	±0.1		±1*		±1	μA
loz	$V_I = V_{IH} \text{ or } V_{IL}, \qquad V_O = V_{CC} \text{ or } GND$	5.5 V		±(	0.25		±2.5		±2.5	μA
Icc	$V_I = V_{CC} \text{ or } GND,  I_O = 0$	5.5 V			4		40		40	μΑ
Ci	$V_{I} = V_{CC}$ or GND	5 V		4	10				10	pF
Co	$V_{O} = V_{CC}$ or GND	5 V		6						pF

\* On products compliant to MIL-PRF-38535, this parameter is not production tested at  $V_{CC}$  = 0 V.



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#### timing requirements over recommended operating free-air temperature range, V<sub>CC</sub> = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

		T <sub>A</sub> = 25°C		T <sub>A</sub> = 25°C SN54AHC373		SN74A	UNIT	
		MIN	MAX	MIN	MAX	MIN	MAX	UNIT
tw	Pulse duration, LE high	5		5		5		ns
t <sub>su</sub>	Setup time, data before LE $\downarrow$	4		4		4		ns
t <sub>h</sub>	Hold time, data after LE $\downarrow$	1		1		1		ns

# timing requirements over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

		T <sub>A</sub> = 25°C		T <sub>A</sub> = 25°C SN54AHC373		SN74A	UNIT	
		MIN	MAX	MIN	MAX	MIN	MAX	UNIT
tw	Pulse duration, LE high	5		5		5		ns
t <sub>su</sub>	Setup time, data before LE $\downarrow$	4		4		4		ns
th	Hold time, data after LE $\downarrow$	1		1		1		ns

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

	FROM	то	LOAD	Τį	λ = 25°C	;	SN54A	HC373	SN74A	HC373	LINUT		
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT		
<sup>t</sup> PLH		Q	0. 45 pF		7.3*	11.4*	1*	13.5*	1	13.5			
<sup>t</sup> PHL	D	Q	C <sub>L</sub> = 15 pF		7.3*	11.4*	1*	13.5*	1	13.5	ns		
<sup>t</sup> PLH	LE	Q	Ci = 15 pE		7*	11*	1*	13*	1	13	ns		
<sup>t</sup> PHL		Q	C <sub>L</sub> = 15 pF		7*	11*	1*	13*	1	13	115		
<sup>t</sup> PZH	OE	Q	C <sub>I</sub> = 15 pF		7.3*	11.4*	1*	13.5*	1	13.5	ns		
<sup>t</sup> PZL	OE	Q			7.3*	11.4*	1*	13.5*	1	13.5	115		
<sup>t</sup> PHZ	OE	Q	C <sub>I</sub> = 15 pF		7*	10*	1*	12*	1	12	ns		
<sup>t</sup> PLZ	UE	Q	3	Q			7*	10*	1*	12*	1	12	115
<sup>t</sup> PLH	D	Q	C <sub>L</sub> = 50 pF		9.8	14.9	1	17	1	17	ns		
<sup>t</sup> PHL	U	Q	CL = 30 pr		9.8	14.9	1	17	1	17	115		
<sup>t</sup> PLH	LE	Q	C <sub>L</sub> = 50 pF		9.5	14.5	1	16.5	1	16.5	ns		
<sup>t</sup> PHL		Q	CL = 30 pr		9.5	14.5	1	16.5	1	16.5	115		
<sup>t</sup> PZH		Q	C <sub>I</sub> = 50 pF		9.8	14.9	1	17	1	17	ns		
<sup>t</sup> PZL	OE	Q	0L = 30 pr		9.8	14.9	1	17	1	17	115		
<sup>t</sup> PHZ	OE	Q	C <sub>I</sub> = 50 pF		9.5	13.2	1	15	1	15	ns		
<sup>t</sup> PLZ		Q	Q	0L = 30 pr		9.5	13.2	1	15	1	15	115	
<sup>t</sup> sk(o)			C <sub>L</sub> = 50 pF			1.5**				1.5	ns		

\* On products compliant to MIL-PRF-38535, this parameter is not production tested.

\*\* On products compliant to MIL-PRF-38535, this parameter does not apply.



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# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

00	-			_	-							
PARAMETER	FROM	то	LOAD	т,	<b>₄ = 25°C</b>	;	SN54A	HC373	SN74A	HC373	UNIT	
	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
<sup>t</sup> PLH	D	Q	C <sub>I</sub> = 15 pF		5*	7.2*	1*	8.5*	1	8.5	ns	
<sup>t</sup> PHL	U	Q			5*	7.2*	1*	8.5*	1	8.5	115	
<sup>t</sup> PLH	LE	Q	C <sub>L</sub> = 15 pF		4.9*	7.2*	1*	8.5*	1	8.5		
<sup>t</sup> PHL		Q	CL = 15 pr		4.9*	7.2*	1*	8.5*	1	8.5	ns	
<sup>t</sup> PZH		Q	C <sub>L</sub> = 15 pF		5.5*	8.1*	1*	9.5*	1	9.5	ns	
<sup>t</sup> PZL	OE	Q	CL = 15 pr		5.5*	8.1*	1*	9.5*	1	9.5	115	
<sup>t</sup> PHZ		Q	0	C <sub>L</sub> = 15 pF		5*	7.2*	1*	8.5*	1	8.5	ns
<sup>t</sup> PLZ	ŌĒ	ÛE	Q			5*	7.2*	1*	8.5*	1	8.5	115
<sup>t</sup> PLH	D	Q	C <sub>1</sub> = 50 pF		6.5	9.2	1	10.5	1	10.5	ns	
<sup>t</sup> PHL	U	Q	CL = 50 pF		6.5	9.2	1	10.5	1	10.5	.5	
<sup>t</sup> PLH	LE	Q	C <sub>L</sub> = 50 pF		6.4	9.2	1	10.5	1	10.5		
<sup>t</sup> PHL		Q	CL = 50 pr		6.4	9.2	1	10.5	1	10.5	ns	
<sup>t</sup> PZH		0			7	10.1	1	11.5	1	11.5		
<sup>t</sup> PZL	ŌĒ	Q	C <sub>L</sub> = 50 pF		7	10.1	1	11.5	1	11.5	5 ns	
<sup>t</sup> PHZ		0	$C_{\rm L} = 50  \rm pF$		6.5	9.2	1	10.5	1	10.5		
<sup>t</sup> PLZ	ŌE	Q	C <sub>L</sub> = 50 pF		6.5	9.2	1	10.5	1	10.5	ns	
<sup>t</sup> sk(o)			C <sub>L</sub> = 50 pF			1**				1	ns	

\* On products compliant to MIL-PRF-38535, this parameter is not production tested.

\*\* On products compliant to MIL-PRF-38535, this parameter does not apply.

# noise characteristics, $V_{CC}$ = 5 V, $C_L$ = 50 pF, $T_A$ = 25°C (see Note 4)

	PARAMETER			UNIT
	FARAIVIETER	MIN	MAX	
V <sub>OL(P)</sub>	Quiet output, maximum dynamic V <sub>OL</sub>		0.8	V
V <sub>OL(V)</sub>	Quiet output, minimum dynamic V <sub>OL</sub>		-0.8	V
VOH(V)	Quiet output, minimum dynamic V <sub>OH</sub>	4.1		V
VIH(D)	High-level dynamic input voltage	3.5		V
V <sub>IL(D)</sub>	Low-level dynamic input voltage		1.5	V

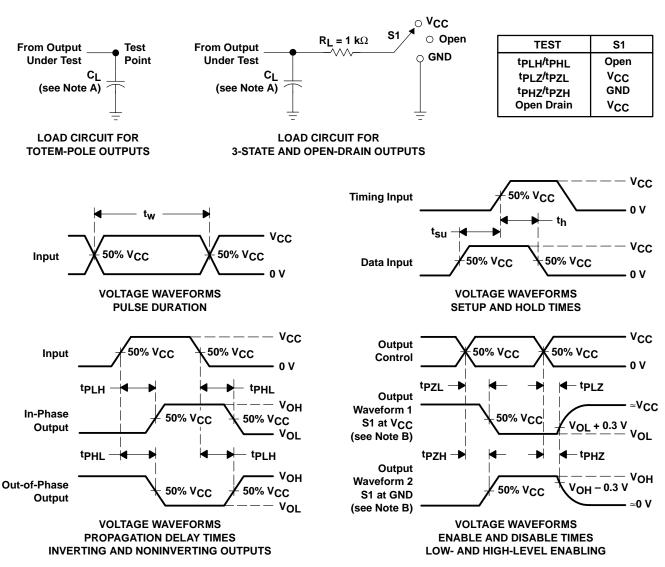
NOTE 4: Characteristics are for surface-mount packages only.

# operating characteristics, $V_{CC}$ = 5 V, $T_A$ = 25°C

	PARAMETER	TEST CO	ONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	No load,	f = 1 MHz	18	pF



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>f</sub>  $\leq$  3 ns, t<sub>f</sub>  $\leq$  3 ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

#### Figure 1. Load Circuit and Voltage Waveforms



9-Oct-2007

## **PACKAGING INFORMATION**

TEXAS INSTRUMENTS www.ti.com

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finis	n MSL Peak Temp <sup>(3)</sup>
5962-9686601Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9686601QRA	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
5962-9686601QSA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type
SN74AHC373DBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI
SN74AHC373DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC373DBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC373DBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC373DGVR	ACTIVE	TVSOP	DGV	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC373DGVRE4	ACTIVE	TVSOP	DGV	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC373DGVRG4	ACTIVE	TVSOP	DGV	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC373DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC373DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC373DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC373DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC373DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC373DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC373N	ACTIVE	PDIP	Ν	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AHC373NE4	ACTIVE	PDIP	Ν	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AHC373NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC373NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC373NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC373PW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC373PWE4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC373PWG4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC373PWLE	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI
SN74AHC373PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC373PWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74AHC373PWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54AHC373FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54AHC373J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54AHC373W	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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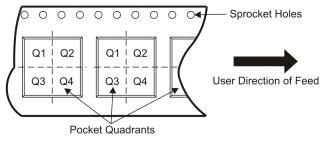
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## TAPE AND REEL INFORMATION





# QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal Device	Package	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHC373DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74AHC373DGVR	TVSOP	DGV	20	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1
SN74AHC373DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74AHC373PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1



# PACKAGE MATERIALS INFORMATION

11-Mar-2008



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHC373DBR	SSOP	DB	20	2000	346.0	346.0	33.0
SN74AHC373DGVR	TVSOP	DGV	20	2000	346.0	346.0	29.0
SN74AHC373DWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN74AHC373PWR	TSSOP	PW	20	2000	346.0	346.0	33.0

MSSO002E - JANUARY 1995 - REVISED DECEMBER 2001

# DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-150



MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

# PW (R-PDSO-G\*\*)

### PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



J (R-GDIP-T\*\*) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

## PLASTIC SMALL-OUTLINE PACKAGE

#### 0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 $\bigcirc$ Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS \*\* 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G\*\*)

**14-PINS SHOWN** 

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



MLCC006B - OCTOBER 1996

### FK (S-CQCC-N\*\*)

#### LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



PLASTIC SMALL-OUTLINE

MPDS006C - FEBRUARY 1996 - REVISED AUGUST 2000

## DGV (R-PDSO-G\*\*)

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
- D. Falls within JEDEC: 24/48 Pins MO-153

14/16/20/56 Pins – MO-194



W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES: A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within Mil-Std 1835 GDFP2-F20



DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AC.



# N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



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